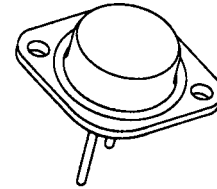



**SOLID STATE DEVICES, INC**

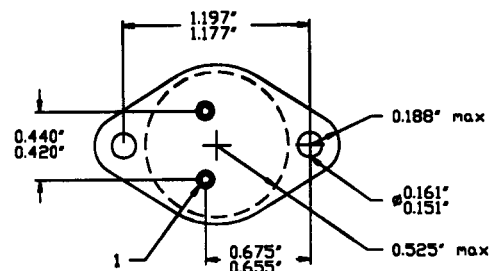
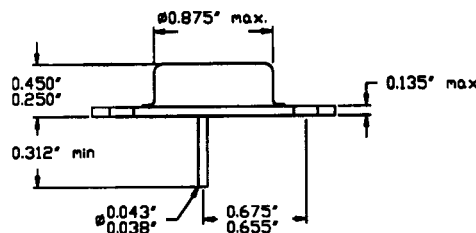
 14849 Firestone Boulevard · La Mirada, CA 90638  
 Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

**SFF9240/3**
**Designer's Data Sheet**
**FEATURES:**

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed
- TX, TXV and Space Level Screening available
- Replaces: IRF9240 Types

**-11 AMP  
-200 VOLTS  
0.50Ω  
P-CHANNEL  
POWER MOSFET**
**TO-3**

**MAXIMUM RATINGS**

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V <sub>DS</sub>	-200	Volts
Gate to Source Voltage	V <sub>GS</sub>	±20	Volts
Continuous Drain Current	I <sub>D</sub>	-9.3	Amps
Operating and Storage Temperature	T <sub>OP</sub> & T <sub>STG</sub>	-55 to +150	°C
Thermal Resistance, Junction to Case	R <sub>θJC</sub>	1.0	°C/W
Total Device Dissipation @ TC=25°C	P <sub>D</sub>	125	Watts
Total Device Dissipation @ TC=55°C		95	

**PACKAGE OUTLINE: TO-3**
**PIN OUT:**
**PIN 1: SOURCE  
PIN 2: GATE  
CASE DRAIN**

**NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.**
**DATA SHEET #: FP0009 A**
**MED**

SFF9240/3

SOLID STATE DEVICES, INC

14849 Firestone Boulevard · La Mirada, CA 90638  
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424ELECTRICAL CHARACTERISTICS @  $T_J=25^\circ\text{C}$  (Unless Otherwise Specified)

RATING	SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage ( $V_{GS}=0\text{ V}$ , $I_{D}=-250\mu\text{A}$ )	$BV_{DSS}$	-200	---	---	V
Drain to Source on State Resistance ( $V_{GS}=-10\text{ V}$ , $I_{D}=-6\text{ A}$ )	$R_{DS(on)}$	---	0.35	0.50	$\Omega$
On State Drain Current ( $V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS}=-10\text{ V}$ )	$I_{D(on)}$	-11	---	---	A
Gate Threshold Voltage ( $V_{DS}=V_{GS}$ , $I_{D}=-250\mu\text{A}$ )	$V_{GS(th)}$	-2.0	---	-4.0	V
Forward Transconductance ( $V_{DS} \geq I_{D(on)} \times R_{DS(on)}$ max., $I_{DS}=-6.0\text{ A}$ )	gfs	4	6	---	$S(\nu)$
Zero Gate Voltage Drain Current ( $V_{DS}=\text{max rated voltage}$ , $V_{GS}=0\text{ V}$ ) ( $V_{DS}=80\%$ rated $V_{DS}$ , $V_{GS}=0\text{ V}$ , $T_A=125^\circ\text{C}$ )	$I_{DSS}$	---	---	-250 -1000	$\mu\text{A}$
Gate to Source Leakage Forward Gate to Source Leakage Reverse	$V_{GS}=\pm 20\text{ V}$ $I_{GSS}$	---	---	-100 100	nA
Total Gate Charge Gate to Source Charge Gate to Drain Charge	$V_{GS}=-15\text{ Volts}$ 80% rated $V_{DS}$ $I_{D}=-22\text{ A}$ $Q_g$ $Q_{gs}$ $Q_{gd}$	---	38 8.0 21	90 ---	nC
Turn on Delay Time Rise Time Turn Off Delay Time Fall Time	$V_{DD}=-100\text{ V}$ $I_{D}=-6\text{ A}$ $R_G=4.7\Omega$ $t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	---	13 45 29 29	30 15 18 12	nsec
Diode Forward Voltage ( $I_S=-11\text{ A}$ , $V_{GS}=0\text{ V}$ , $T_J=25^\circ\text{C}$ )	$V_{SD}$	---	---	-4.6	V
Diode Reverse Recovery Time Reverse Recovery Charge	$T_J=150^\circ\text{C}$ $I_F=-11\text{ A}$ $di/dt=100\text{ A/sec}$ $t_{rr}$ $Q_{RR}$	---	270 2.0	---	nsec $\mu\text{C}$
Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{GS}=0\text{ Volts}$ $V_{DS}=-25\text{ Volts}$ $f=1\text{ MHz}$ $C_{iss}$ $C_{oss}$ $C_{rss}$	---	1100 375 150	1300 450 250	pF

SAFE OPERATING AREA (S.O.A.)  
 $T_C = 25^\circ\text{C}$ , D.C. CONDITION